

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	22	electrode and flexible with reinforc\$3 with bond\$3 and adhesive with flexible	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/31 19:24			0
2	BRS	130	electrode with bump and flexible with bond\$3 and adhesive with flexible	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/12 22:33			0
3	BRS	1	electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3 with groove	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/12 22:34			0
4	BRS	22	electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/12 22:51			0
5	BRS	12	electrode with bump and flexible with bond\$3 and adhesive with resin and adhesive with flexible and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/12 22:52			0
6	IS&R	2	("5637800"). PN.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 17:13			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
7	BRS	6	5637800.URPN .	USPAT	2003/05/30 17:10			0
8	IS&R	2	("4965653").PN.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 17:18			0
9	BRS	10	4965653.URPN .	USPAT	2003/05/30 17:14			0
10	IS&R	2	("6280828").PN.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 17:20			0
11	BRS	1	6280828.URPN .	USPAT	2003/05/30 17:18			0
12	BRS	3	("5372871" "5621333" "5864470").PN.	USPAT	2003/05/30 17:19			0
13	BRS	1978	"flexible wiring board"	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/31 21:55			0
14	BRS	444	"flexible wiring board" and electrode	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 17:21			0
15	BRS	154	"flexible wiring board" and electrode and adhesive	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 20:05			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
16	BRS	3	"flexible wiring board" and electrode and adhesive and reinforc\$3 and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 17:24			0
17	BRS	30	"flexible wiring board" and electrode and adhesive and reinforc\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 20:04			0
18	BRS	4	"flexible wiring board" and electrode and adhesive with carrier	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 17:50			0
19	BRS	3	"flexible wiring board" and electrode and adhesive and reinforc\$3 and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 20:05			0
20	BRS	21	"flexible wiring board" and electrode and adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 20:38			0
21	BRS	2	bump with front with surface and reinforcement with back with surface with adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 21:11			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
22	BRS	2	pad with front with surface and reinforcement with back with surface with adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 21:11			0
23	BRS	3	reinforcement with back with surface with adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 22:47			0
24	BRS	200	circuit with board and back with surface with adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 21:20			0
25	BRS	79	circuit with board and back with surface with adhesive with bond\$3 and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 21:20			0
26	BRS	25	circuit with board and substrate with back with surface with adhesive with bond\$3 and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/31 21:09			0
27	BRS	4	front with pad and substrate with back with surface with adhesive with bond\$3 and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 21:58			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
28	BRS	1	front with pad and substrate with back with surface with adhesive with bond\$3 and dicing	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 21:59			0
29	BRS	1	pad and substrate with back with surface with adhesive with bond\$3 and dicing and etch\$3 with back with wafer	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 22:12			0
30	BRS	1	bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and etch\$3 with back with wafer	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 22:14			0
31	BRS	2	bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and polish\$3 with back with wafer	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 22:14			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
32	BRS	1	bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and remov\$3 with back with wafer	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 22:15			0
33	BRS	2	bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and grind\$3 with back with wafer	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 22:21			0
34	BRS	3	6184064.URPN .	USPAT	2003/05/30 22:16			0
35	BRS	1	bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and thin\$4 with back with wafer	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 22:27			0
36	IS&R	2	("6429506").PN.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 22:27			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
37	BRS	2	reinforc\$5 with hold\$3 same hand\$4 and surface with adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 22:50			0
38	BRS	2	reinforc\$5 with hold\$3 same hand\$4 and semiconductor and adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 22:51			0
39	BRS	15	pad and flexible with reinforc\$3 and wafer with dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/31 19:25			0
40	BRS	9	electrode and flexible with reinforc\$3 and wafer with dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/31 19:42			0
41	BRS	4	bond with pad and adhesive and flexible with reinforc\$3 and wafer with dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/31 19:47			0
42	BRS	46	bond with pad and adhesive with flexible with substrate and wafer with dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/31 20:26			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
43	BRS	27	bond and pad and ball and adhesive with flexible with substrate and wafer with dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/31 20:27			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	22	electrode and flexible with reinforc\$3 with bond\$3 and adhesive with flexible	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/31 19:24			0
2	BRS	130	electrode with bump and flexible with bond\$3 and adhesive with flexible	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/12 22:33			0
3	BRS	1	electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3 with groove	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/12 22:34			0
4	BRS	22	electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/12 22:51			0
5	BRS	12	electrode with bump and flexible with bond\$3 and adhesive with resin and adhesive with flexible and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/12 22:52			0
6	IS& R	2	("5637800"). PN.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 17:13			0

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9	BRS	10	4965653.URPN .	USPAT	2003/05/30 17:14			0
10	IS&R	2	("6280828").PN.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 17:20			0
11	BRS	1	6280828.URPN .	USPAT	2003/05/30 17:18			0
12	BRS	3	("5372871" "5621333" "5864470").PN.	USPAT	2003/05/30 17:19			0
13	BRS	1978	"flexible wiring board"	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/31 21:55			0
14	BRS	444	"flexible wiring board" and electrode	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 17:21			0
15	BRS	154	"flexible wiring board" and electrode and adhesive	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 20:05			0

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18	BRS	4	"flexible wiring board" and electrode and adhesive with carrier	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 17:50			0
19	BRS	3	"flexible wiring board" and electrode and adhesive and reinforc\$3 and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 20:05			0
20	BRS	21	"flexible wiring board" and electrode and adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 20:38			0
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	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
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31	BRS	2	bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and polish\$3 with back with wafer	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 22:14			0

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36	IS&R	2	("6429506"). PN.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/05/30 22:27			0

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38	BRS	2	reinforc\$5 with hold\$3 same hand\$4 and semiconductor and adhesive and dic\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2003/0 5/30 22:51			0
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